

Product Change Notification - RMES-10TYKT692

Data	•
Date	•

16 Jan 2019

Product Category:

Motor Drivers

Affected CPNs:



Notification subject:

CCB 3674 Initial Notice: Qualification of NSEB as a new assembly site for selected products available in 8L DFN (4x4x0.9mm) package.

Notification text:

PCN Status:

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of NSEB as a new assembly site for selected products available in 8L DFN (4x4x0.9mm) package.

Pre Change:

Assembled at LPI using gold (Au) bond wire, 8340 die attach, G770HT molding compound and C194 lead frame material.

Post Change:

Assembled at NSEB using gold (Au) bond wire, 8600 die attach, G700LTD molding compound and C194 lead frame material.

Pre and Post Change Summary:

	Pre Change	Post Change
Accombly Site	Lingsen Precision	UTAC Thai Limited (UTL-1)
Assembly Site	Industries, LTD. (LPI)	LTD. (NSEB)
Wire material	Au	Au
Die attach material	8340	8600
Molding compound material	G770HT	G700LTD
Lead frame material	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity and on-time delivery performance by qualifying NBEB as a new assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:



March 2019

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	January 2019				March 2019						
Workweek	01	02	03	04	05	->	09	10	11	12	13
Initial PCN Issue Date			X								
Qual Report Availability							X				
Final PCN Issue Date							X				

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:

January 16, 2019: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_RMES-10TYKT692_Qual__Plan.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile, including opt out,</u> please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

RMES-10TYKT692 - CCB 3674 8L DFN (4x4x0.9mm) package.	nitial Notice: Qualification of NSEB as a new assembly site for selected products available
Affected Catalog Part Numbers (C	PN)
MCP8063-E/MD	
MCP8063-E/MDVAO	
MCP8063T-E/MD	

Date: Tuesday, January 15, 2019